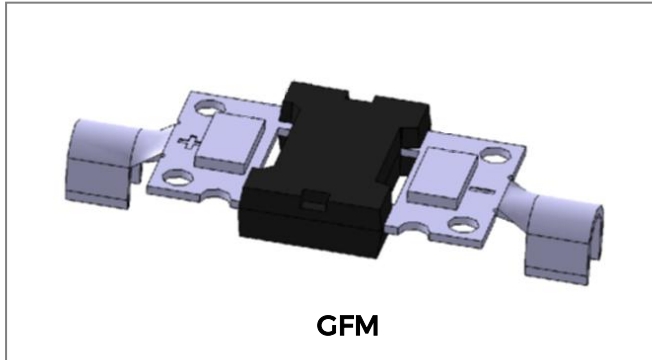


## GF6145TC Power Schottky Module Bypass Diode



### Features

- Low thermal resistance
- Lower forward voltage drop, low power loss
- Isolate Package design, ideal for heat dispersion
- High forward current capability
- Excellent anti-humidity
- Low profile package
- High forward surge capability
- Trench MOS Schottky technology
- All SMC parts are traceable to the wafer lot
- Additional electrical and life testing can be performed upon request

### Mechanical Data

- Case: GFM
- Terminals: Copper
- High temperature soldering guaranteed
- Heated-tool welding 260°C, 10seconds
- Marking Code: GF6145TC

### Maximum Ratings (limiting values, at 25 °C unless otherwise specified)

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	-	45	V
Average Rectified Forward Current	$I_{F(AV)}$	$T_C = 96^\circ\text{C}$ , In DC	60	A
Peak One Cycle Non-Repetitive Surge Current	$I_{FSM}$	8.3 ms, half Sine pulse	450	A

### Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop*	$V_{F1}$	@ 60A, Pulse, $T_J = 25^\circ\text{C}$	0.47	0.6	V
Reverse Current*	$I_{R1}$	@ $V_R = \text{rated } V_R$ , $T_J = 25^\circ\text{C}$	0.05	0.5	mA
Junction Capacitance	$C_T$	@ $V_R = 5\text{V}$ , $T_C = 25^\circ\text{C}$ $f_{SIG} = 1\text{MHz}$	9836	-	pF

\* Pulse width < 300  $\mu\text{s}$ , duty cycle < 2%

Technical Data  
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**Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	$T_J$	IN DC Forward Mode, without reverse bias, $t \leq 1$ h	-55 to +200	$^{\circ}\text{C}$
Storage Temperature	$T_{\text{stg}}$	-	-55 to +150	$^{\circ}\text{C}$
Typical Thermal Resistance Junction to Case	$R_{\theta\text{JC}}$	-	1.5	$^{\circ}\text{C}/\text{W}$

**Ratings and Characteristics Curves**

Figure1 Typical Forward Characteristics

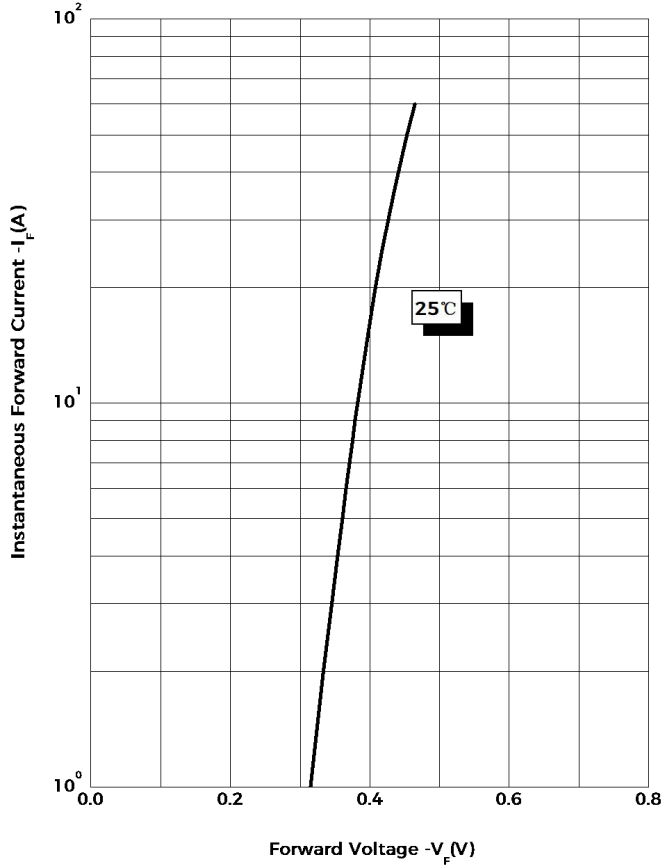


Figure 2 Typical Reverse Characteristics

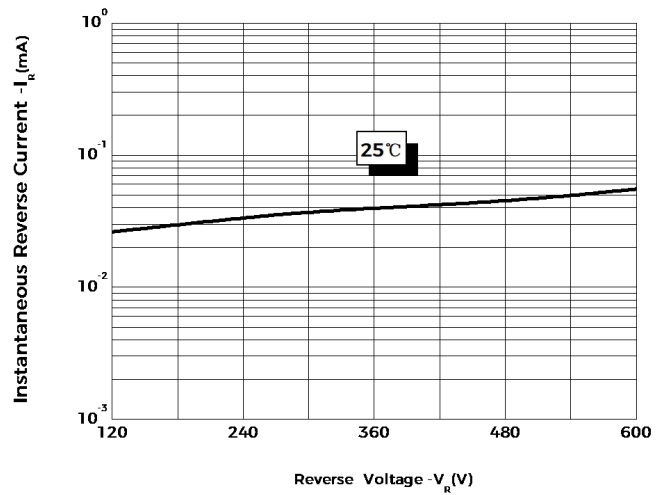
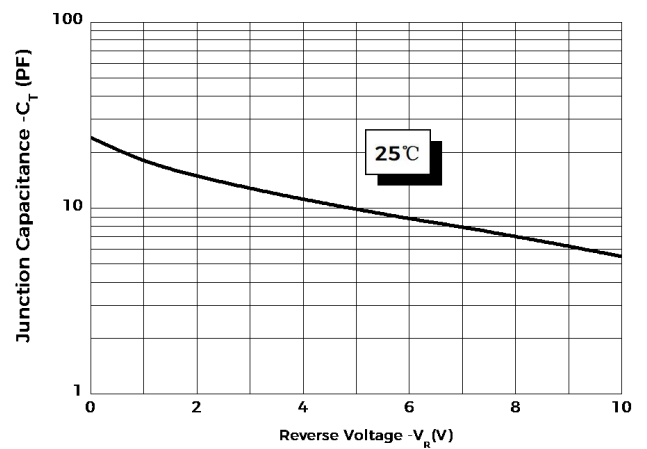


Figure 3 Typical Junction Capacitance

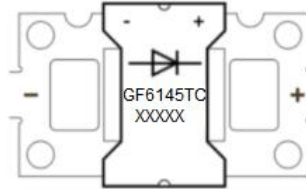


Technical Data  
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**Ordering Information**

Device	Package	Shipping
GF6145TC	GFM	30pcs / Tube

**Marking Diagram**

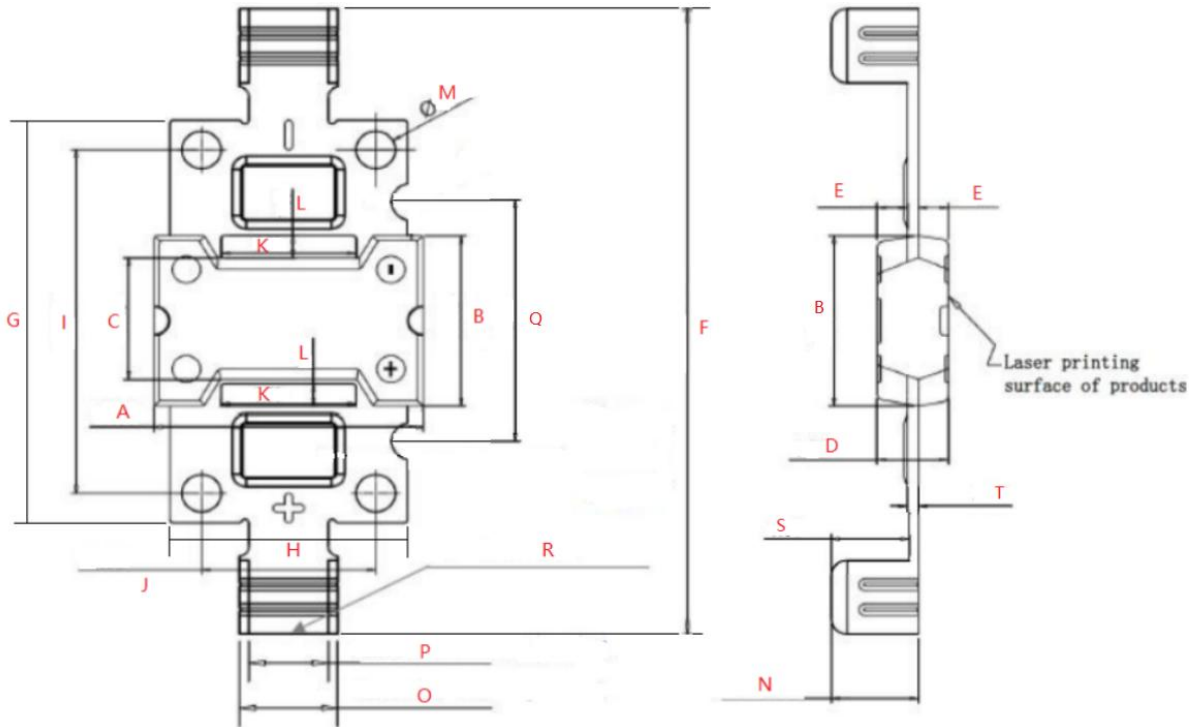


Where XXXXX is YYWWL

GF6145TC = Marking Code  
YY = Year  
WW = Week  
L = Lot Number

Order P/N	Terminals	Additional
GF6145TC-S1	Tin Plated	None
GF6145TC-S3	Tin Plated	Solder Block

**Mechanical Dimensions GFM (Millimeters)**



Symbol	Dimensions in millimeters		
	Min.	Typical	Max
A	16.90	17.00	17.10
B	11.38	11.48	11.58
C	8.15	8.20	8.25
D	4.40	4.50	4.60
E	1.85	1.90	1.95
F	41.90	42.00	42.10
G	26.90	27.00	27.10
H	14.90	15.00	15.60
I	22.90	23.00	23.10
J	10.90	11.00	11.10
K	-	8.50	-
L	-	1.50	-
M	-	Ø2.50	2.55
N	5.35	5.50	5.65
O	6.20	6.30	6.40
P	4.90	5.00	5.10
Q	15.95	16.00	16.05
R	2.80	2.90	3.00
S	4.75	4.80	4.85
T	0.67	0.70	0.73

Dimension H includes Burrs/cutting residuals.

**Technical Data**  
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